

20-3300 HIGH TEMPERATURE AND THERMAL SHOCK EPOXY

DESCRIPTION:

20-3300 is a two part epoxy system formulated to meet the most critical electronic encapsulating requirements. This system has low shrinkage, high tensile and compressive strength.

20-3300 is ideal for high heat and thermal shock exposure. It has excellent adhesion to most substrates and forms a hermetic like seal to protect encapsulated parts. Great choice for high voltage applications.

20-3300 has a convenient 1:1 mix ratio with an extended pot life.

TYPICAL SPECIFICATIONS:

Mix ratio, by weight	1:1
Mixed viscosity @ 25°C, cps	12,000
Pot life, 100 gram mass @ 25°C	45 Hours
Specific gravity @ 25°C	1.40
Hardness, shore D	87
Tensile strength, psi	7,500
Compressive strength, psi	20,000
Thermal expansion coefficient per °C	38×10^{-6}
Operating temperature, °C	-70 to +260
Thermal conductivity, W/m- °K	0.58
Dielectric strength, V/mil	450
Dielectric constant, 60 Hz	4.0
Dissipation factor, 60 Hz	0.01
Volume resistivity, ohm-cm	3.3×10^{15}

INSTRUCTIONS FOR USE:

1. Resin and Catalyst may be heated to 80°C before mixing to reduce the viscosity.
2. By weight, thoroughly mix equal parts 20-3300 Resin and 20-3300 Catalyst. Pot life is 45 hours in a 100 gram mass.
3. Pour and cure for 2 hours at 145°C.

IMPORTANT:

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